

## SSM6L40TU

- Power Management Switch Applications
- High-Speed Switching Applications

- N-ch: 4.0-V drive  
P-ch: 4.0 -V drive
- N-ch, P-ch, 2-in-1
- Low ON-resistance
  - Q1 N-ch:  $R_{on} = 182 \text{ m}\Omega$  (max) (@ $V_{GS} = 4 \text{ V}$ )  
 $R_{on} = 122 \text{ m}\Omega$  (max) (@ $V_{GS} = 10 \text{ V}$ )
  - Q2 P-ch:  $R_{on} = 403 \text{ m}\Omega$  (max) (@ $V_{GS} = -4 \text{ V}$ )  
 $R_{on} = 226 \text{ m}\Omega$  (max) (@ $V_{GS} = -10 \text{ V}$ )

### Q1 Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

| Characteristics      | Symbol    | Rating   | Unit |
|----------------------|-----------|----------|------|
| Drain-source voltage | $V_{DSS}$ | 30       | V    |
| Gate-source voltage  | $V_{GSS}$ | $\pm 20$ | V    |
| Drain current        | DC        | $I_D$    | A    |
|                      | Pulse     | $I_{DP}$ |      |
|                      |           | 1.6      |      |
|                      |           | 3.2      |      |

### Q2 Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

| Characteristics      | Symbol    | Rating   | Unit |
|----------------------|-----------|----------|------|
| Drain-source voltage | $V_{DSS}$ | -30      | V    |
| Gate-source voltage  | $V_{GSS}$ | $\pm 20$ | V    |
| Drain current        | DC        | $I_D$    | A    |
|                      | Pulse     | $I_{DP}$ |      |
|                      |           | -1.4     |      |
|                      |           | -2.8     |      |

### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ ) (Q1, Q2 Common)

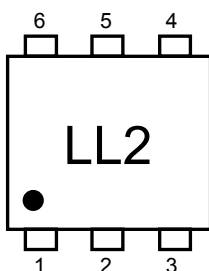
| Characteristics           | Symbol         | Rating     | Unit             |
|---------------------------|----------------|------------|------------------|
| Drain power dissipation   | $P_D$ (Note 1) | 500        | mW               |
| Channel temperature       | $T_{ch}$       | 150        | $^\circ\text{C}$ |
| Storage temperature range | $T_{stg}$      | -55 to 150 | $^\circ\text{C}$ |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

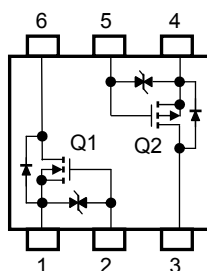
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: Mounted on an FR4 board. (total dissipation)  
(25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm, Cu Pad : 645 mm<sup>2</sup>)

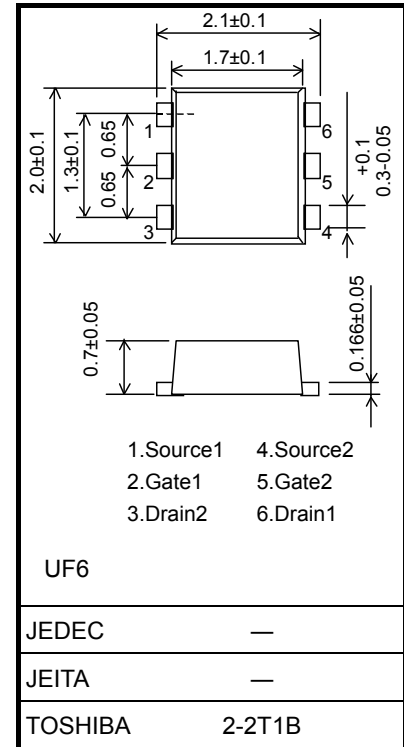
### Marking



### Equivalent Circuit (top view)



Unit: mm



Weight: 7.0 mg (typ.)

Start of commercial production  
2008-02

## Q1 Electrical Characteristics (Ta = 25°C)

| Characteristics                | Symbol         | Test Conditions                                                                                       | Min | Typ. | Max     | Unit             |
|--------------------------------|----------------|-------------------------------------------------------------------------------------------------------|-----|------|---------|------------------|
| Drain-source breakdown voltage | $V_{(BR) DSS}$ | $I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$                                                            | 30  | —    | —       | V                |
|                                | $V_{(BR) DSX}$ | $I_D = 1 \text{ mA}, V_{GS} = -20 \text{ V}$                                                          | 15  | —    | —       |                  |
| Drain cutoff current           | $I_{DSS}$      | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$                                                         | —   | —    | 1       | $\mu\text{A}$    |
| Gate leakage current           | $I_{GSS}$      | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$                                                     | —   | —    | $\pm 1$ | $\mu\text{A}$    |
| Gate threshold voltage         | $V_{th}$       | $V_{DS} = 5 \text{ V}, I_D = 1 \text{ mA}$                                                            | 1.0 | —    | 2.6     | V                |
| Forward transfer admittance    | $ Y_{fs} $     | $V_{DS} = 5 \text{ V}, I_D = 1 \text{ A}$ (Note 2)                                                    | 1.9 | 3.7  | —       | S                |
| Drain-source ON-resistance     | $R_{DS(ON)}$   | $I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 2)                                                   | —   | 96   | 122     | $\text{m}\Omega$ |
|                                |                | $I_D = 0.5 \text{ A}, V_{GS} = 4 \text{ V}$ (Note 2)                                                  | —   | 130  | 182     |                  |
| Input capacitance              | $C_{iss}$      | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$                                      | —   | 180  | —       | pF               |
| Output capacitance             | $C_{oss}$      |                                                                                                       | —   | 34   | —       |                  |
| Reverse transfer capacitance   | $C_{rss}$      |                                                                                                       | —   | 27   | —       |                  |
| Total Gate Charge              | $Q_g$          | $V_{DS} = 15 \text{ V}, I_D = 1.6 \text{ A}, V_{GS} = 10 \text{ V}$                                   | —   | 5.1  | —       | nC               |
| Gate-Source Charge             | $Q_{gs}$       |                                                                                                       | —   | 3.9  | —       |                  |
| Gate-Drain Charge              | $Q_{gd}$       |                                                                                                       | —   | 1.2  | —       |                  |
| Switching time                 | Turn-on time   | $V_{DD} = 15 \text{ V}, I_D = 0.5 \text{ A}$<br>$V_{GS} = 0 \text{ to } 4 \text{ V}, R_G = 10 \Omega$ | —   | 9.5  | —       | ns               |
|                                | Turn-off time  |                                                                                                       | —   | 9.0  | —       |                  |
| Drain-source forward voltage   | $V_{DSF}$      | $I_D = -1.6 \text{ A}, V_{GS} = 0 \text{ V}$ (Note 2)                                                 | —   | -0.8 | -1.2    | V                |

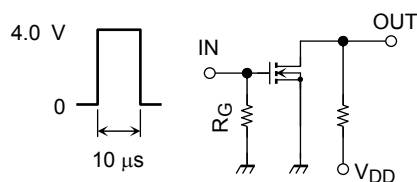
## Q2 Electrical Characteristics (Ta = 25°C)

| Characteristics                | Symbol         | Test Conditions                                                                                         | Min  | Typ. | Max     | Unit             |
|--------------------------------|----------------|---------------------------------------------------------------------------------------------------------|------|------|---------|------------------|
| Drain-source breakdown voltage | $V_{(BR) DSS}$ | $I_D = -1 \text{ mA}, V_{GS} = 0 \text{ V}$                                                             | -30  | —    | —       | V                |
|                                | $V_{(BR) DSX}$ | $I_D = -1 \text{ mA}, V_{GS} = +20 \text{ V}$                                                           | -15  | —    | —       |                  |
| Drain cutoff current           | $I_{DSS}$      | $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$                                                          | —    | —    | -10     | $\mu\text{A}$    |
| Gate leakage current           | $I_{GSS}$      | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$                                                       | —    | —    | $\pm 1$ | $\mu\text{A}$    |
| Gate threshold voltage         | $V_{th}$       | $V_{DS} = -5 \text{ V}, I_D = -1 \text{ mA}$                                                            | -0.8 | —    | -2.0    | V                |
| Forward transfer admittance    | $ Y_{fs} $     | $V_{DS} = -5 \text{ V}, I_D = -1 \text{ A}$ (Note 2)                                                    | 1.0  | 2.0  | —       | S                |
| Drain-source ON-resistance     | $R_{DS(ON)}$   | $I_D = -1.0 \text{ A}, V_{GS} = -10 \text{ V}$ (Note 2)                                                 | —    | 175  | 226     | $\text{m}\Omega$ |
|                                |                | $I_D = -0.5 \text{ A}, V_{GS} = -4.0 \text{ V}$ (Note 2)                                                | —    | 290  | 403     |                  |
| Input capacitance              | $C_{iss}$      | $V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$                                       | —    | 120  | —       | pF               |
| Output capacitance             | $C_{oss}$      |                                                                                                         | —    | 32   | —       |                  |
| Reverse transfer capacitance   | $C_{rss}$      |                                                                                                         | —    | 21   | —       |                  |
| Total Gate Charge              | $Q_g$          | $V_{DS} = -15 \text{ V}, I_D = -1.4 \text{ A}, V_{GS} = -10 \text{ V}$                                  | —    | 2.9  | —       | nC               |
| Gate-Source Charge             | $Q_{gs}$       |                                                                                                         | —    | 2.2  | —       |                  |
| Gate-Drain Charge              | $Q_{gd}$       |                                                                                                         | —    | 0.7  | —       |                  |
| Switching time                 | Turn-on time   | $V_{DD} = -15 \text{ V}, I_D = -1 \text{ A},$<br>$V_{GS} = 0 \text{ to } -4 \text{ V}, R_G = 10 \Omega$ | —    | 12   | —       | ns               |
|                                | Turn-off time  |                                                                                                         | —    | 8.5  | —       |                  |
| Drain-source forward voltage   | $V_{DSF}$      | $I_D = 1.4 \text{ A}, V_{GS} = 0 \text{ V}$ (Note 2)                                                    | —    | 0.87 | 1.2     | V                |

Note 2: Pulse test

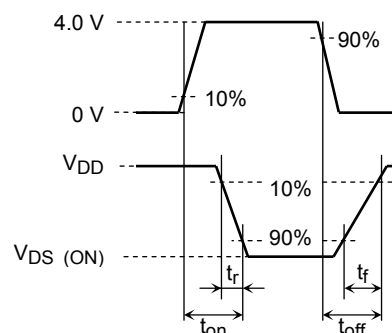
## Q1 Switching Time Test Circuit

### (a) Test Circuit

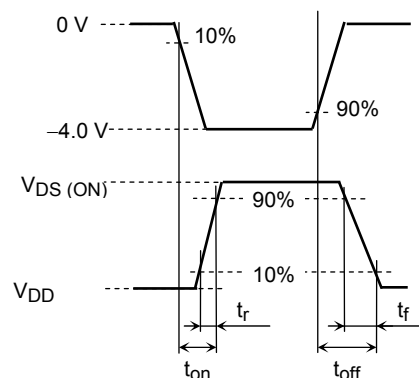


$V_{DD} = 15 \text{ V}$   
 $R_G = 10 \text{ } \Omega$   
 Duty  $\leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5 \text{ ns}$   
 Common Source  
 $T_a = 25^\circ\text{C}$

### (b) $V_{IN}$

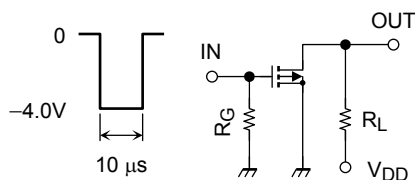


### (c) $V_{OUT}$



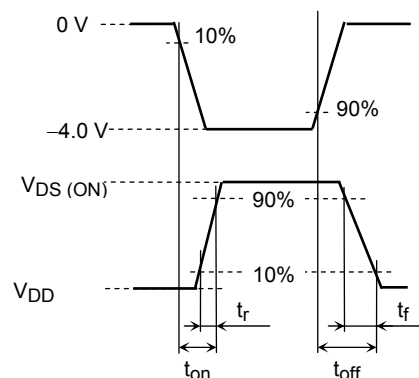
## Q2 Switching Time Test Circuit

### (a) Test Circuit



$V_{DD} = -15 \text{ V}$   
 $R_G = 10 \text{ } \Omega$   
 Duty  $\leq 1\%$   
 $V_{IN}$ :  $t_r, t_f < 5 \text{ ns}$   
 Common Source  
 $T_a = 25^\circ\text{C}$

### (b) $V_{IN}$



### (c) $V_{OUT}$

## Q1 Usage Considerations

Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to be below (1 mA for the Q1 of the SSM6L40TU). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ .

Take this into consideration when using the device.

## Q2 Usage Considerations

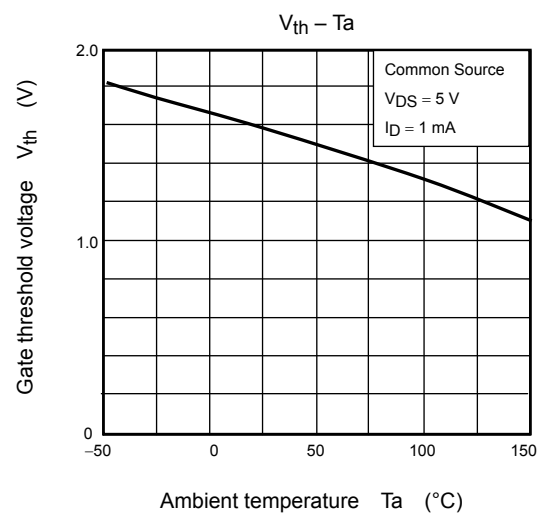
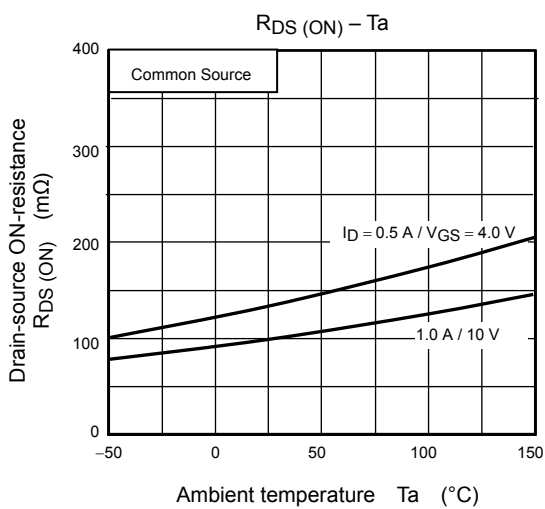
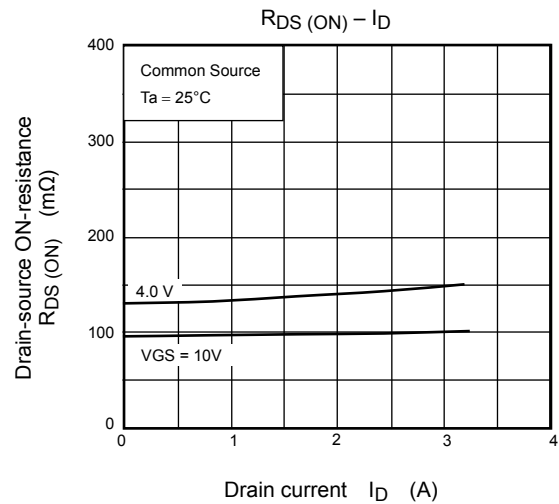
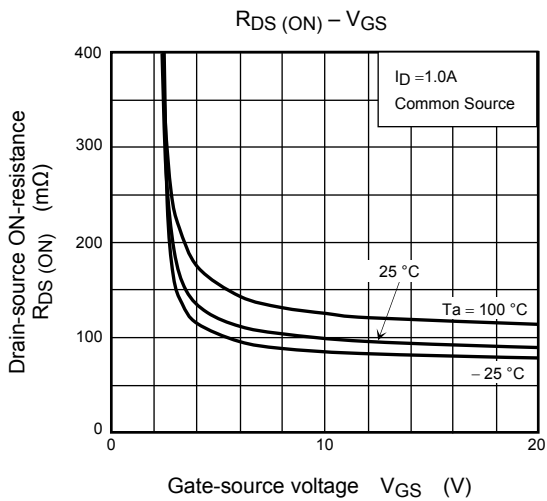
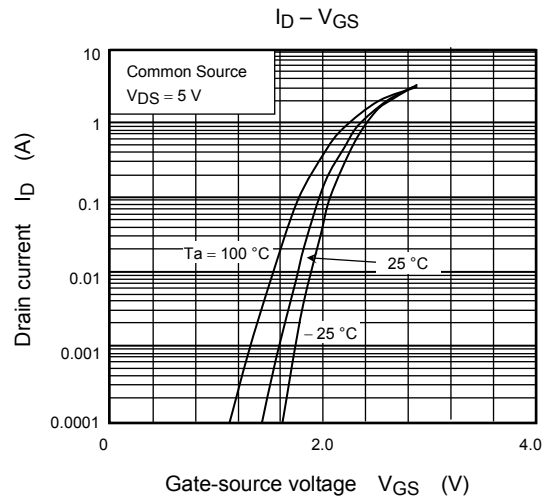
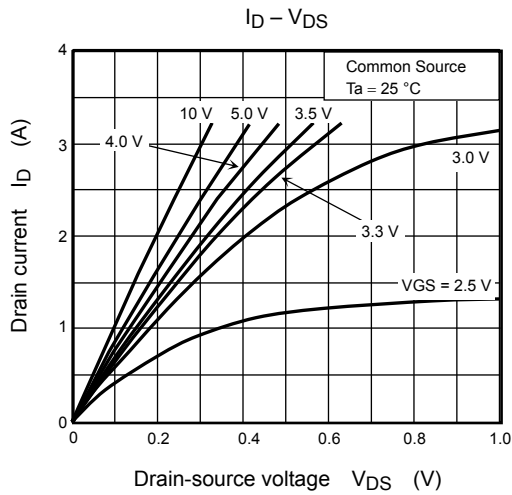
Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to be below (-1 mA for the Q2 of the SSM6L40TU). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ .

Take this into consideration when using the device.

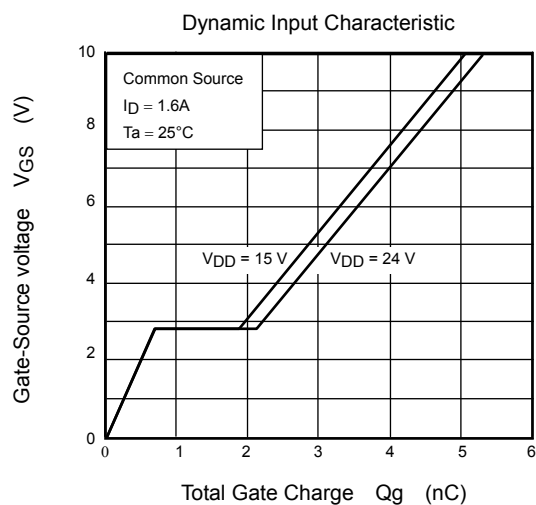
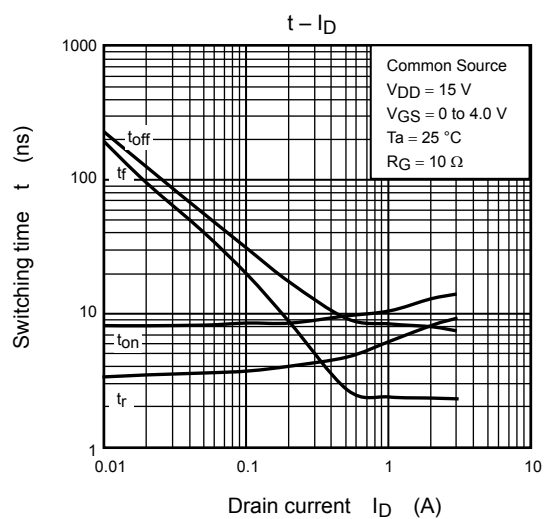
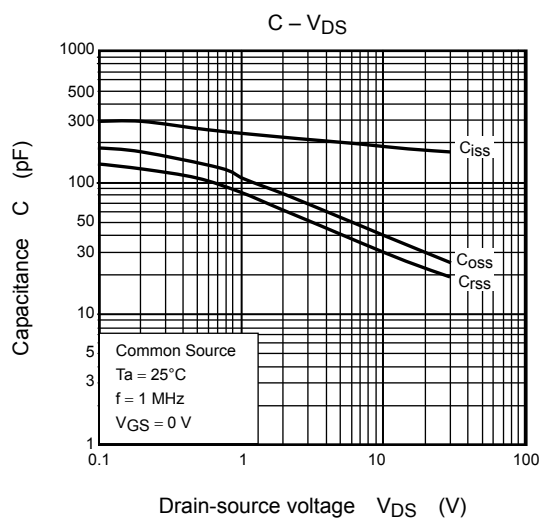
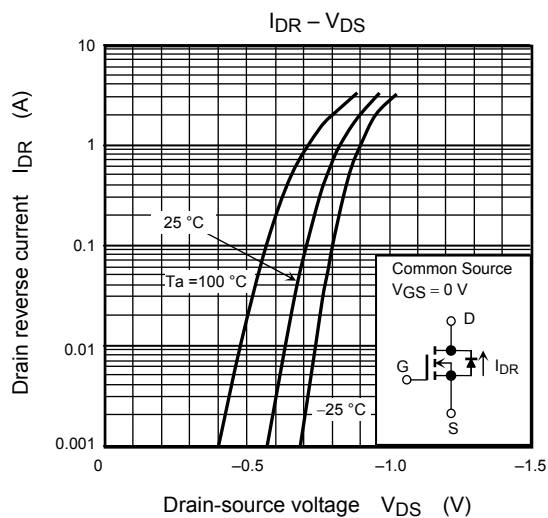
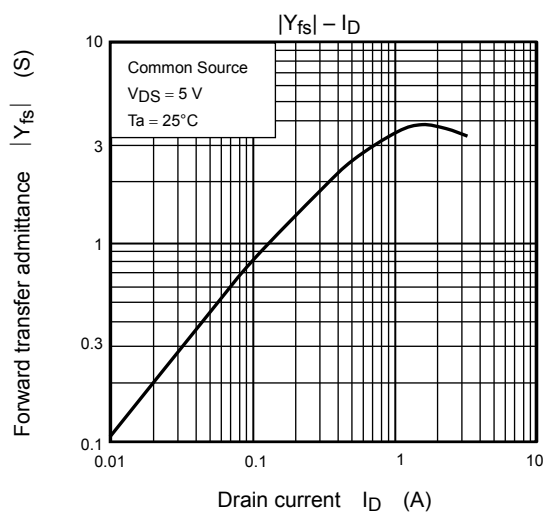
## Handling Precaution

When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

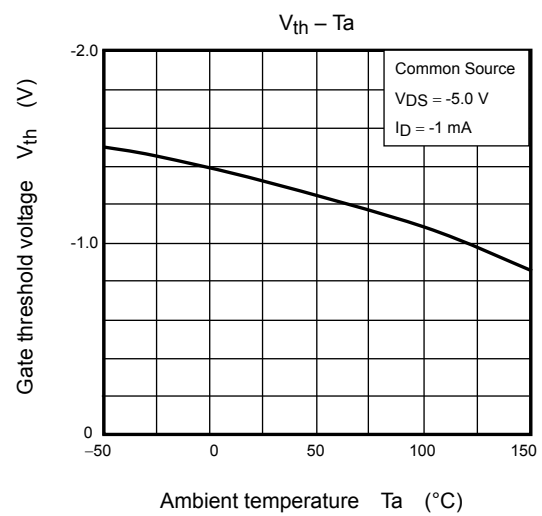
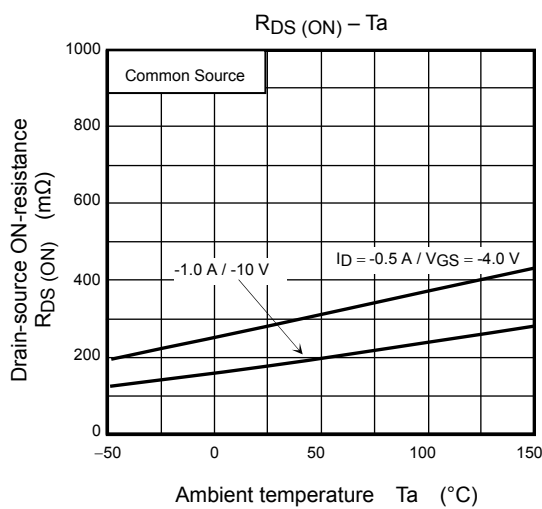
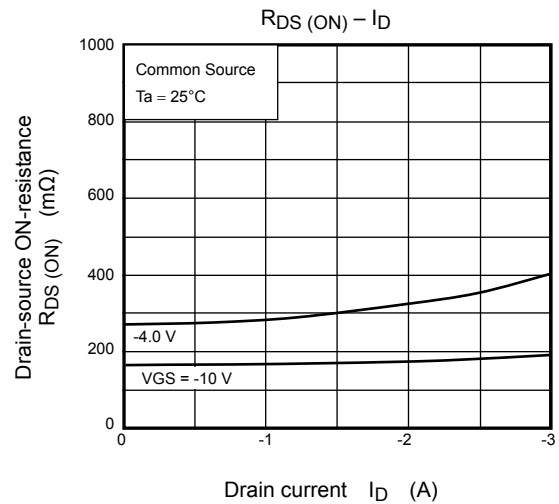
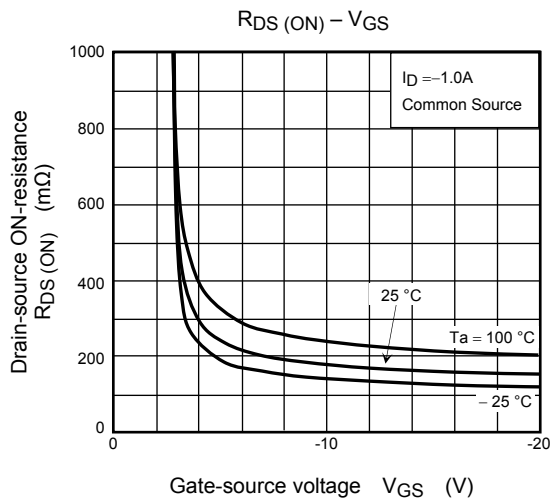
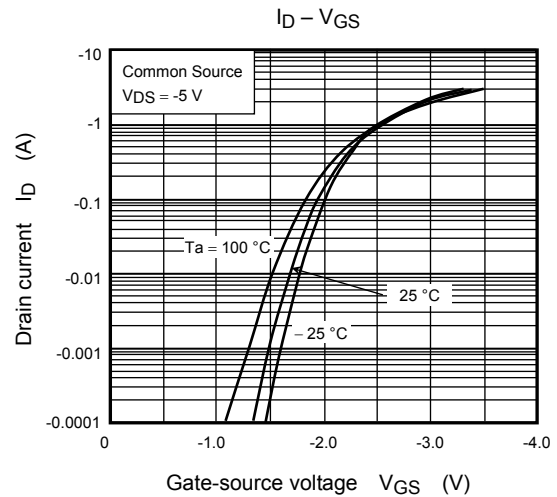
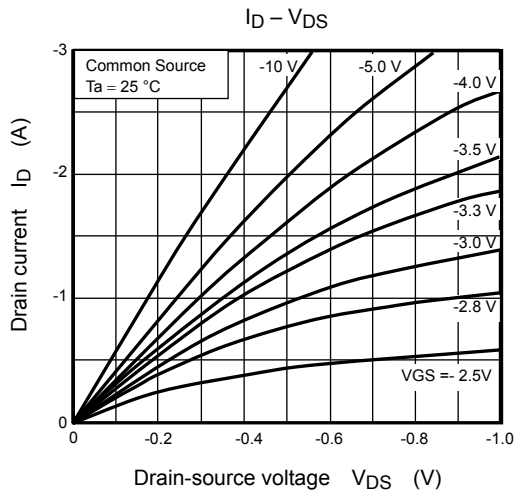
## Q1 (N-ch MOSFET)



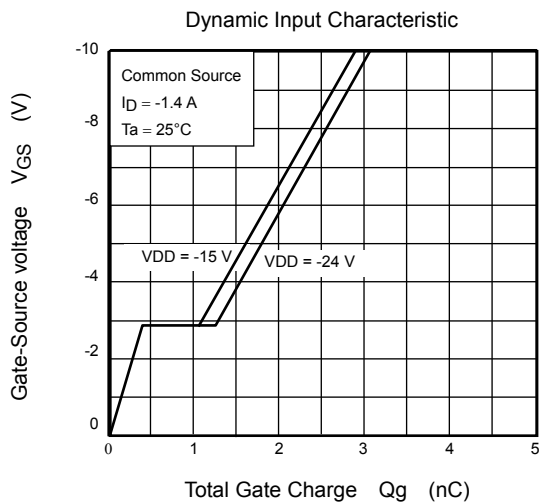
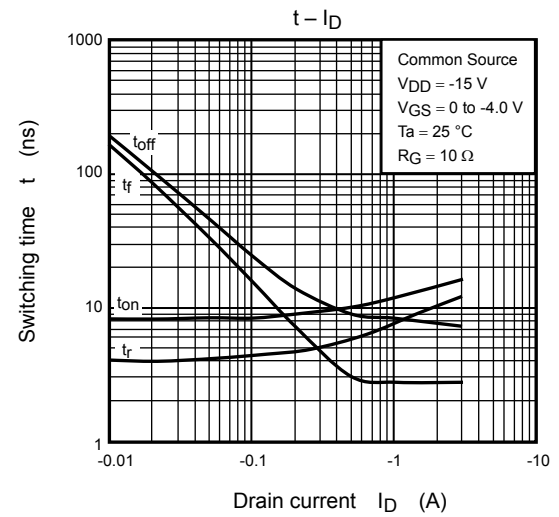
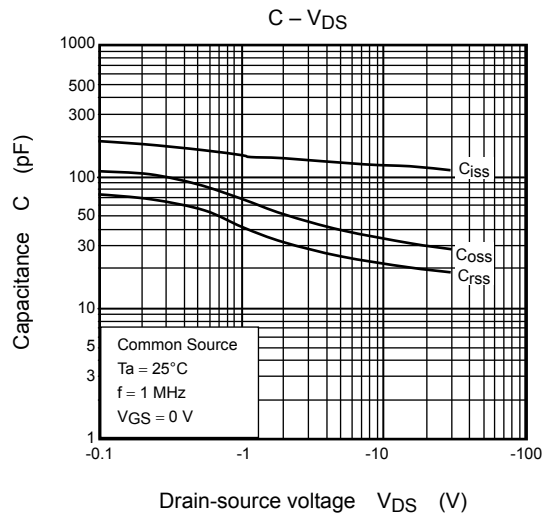
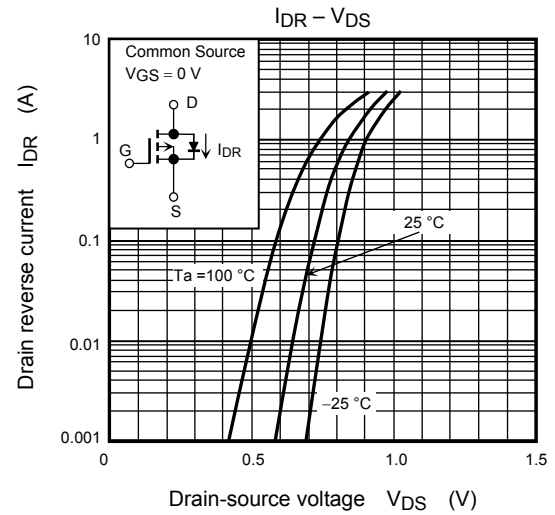
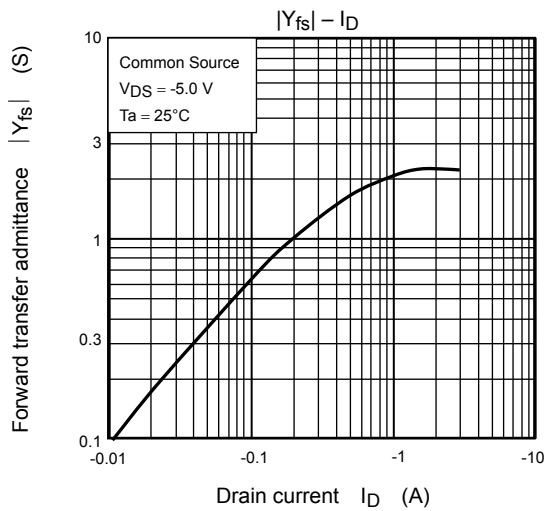
## Q1 (N-ch MOSFET)



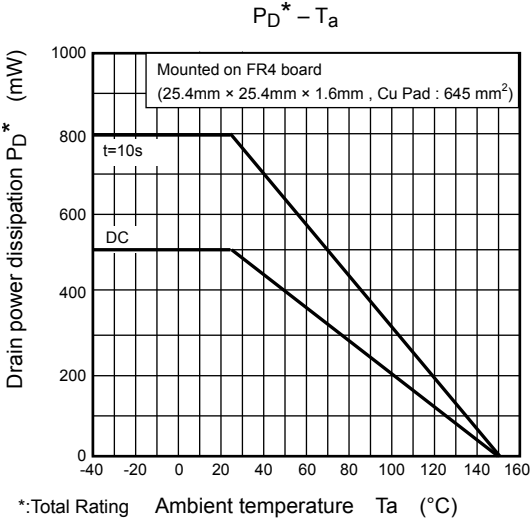
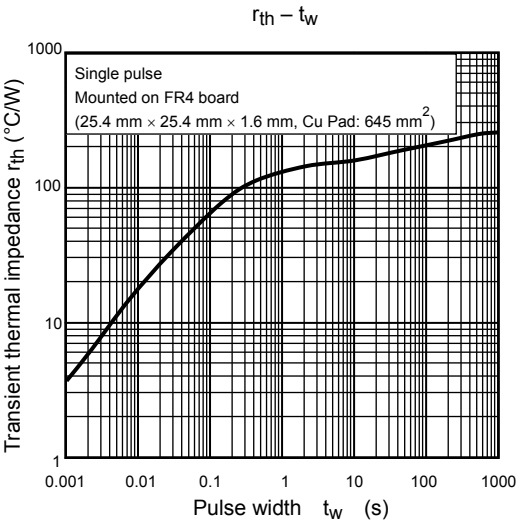
## Q2 (P-ch MOSFET)



## Q2 (P-ch MOSFET)



Q1, Q2 Common



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- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



## JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели,  
кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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